

Serial No. 10/668,408

In the Specification:

Please delete the existing ABSTRACT and replace with the following new ABSTRACT:

ABSTRACT OF THE DISCLOSURE

The present invention is directed to a method for controlled environment processing of parts in a chamber or chambers wherein solvents and/or solutions used for processing the parts can be introduced. The process includes applying a negative gauge pressure to the chamber to remove air or other non-condensable gases. Next a solvent, solvent mixture or solution in either a liquid or vapor state is introduced to the chamber. A first system is then applied to recover the solvent(s) or solution(s) from the object being processed and chamber, and a second system, separate from the first system, is applied that further recovers residual solvent or solution from the object and chamber. Treatment of the part may be in the form of coating, etching, deposition, cleaning, stripping, plating, adhesion, dissolving, penetrating, anodizing, impregnating, debinding or any other process in which material is removed or deposited on a solid surface by transfer from or to a liquid or gas phase.